

# Semiconductor Packaging Materials Market - Forecasts from 2019 to 2024

<https://marketpublishers.com/r/SEE259008AF8EN.html>

Date: October 2019

Pages: 109

Price: US\$ 3,950.00 (Single User License)

ID: SEE259008AF8EN

## Abstracts

Semiconductor packaging material market is projected to grow at a CAGR of 1.16% during the forecast period, reaching the total market size of US\$27.675 billion from US\$25.826 billion in 2018. Semiconductor packaging material is used for the protection of ICs and semiconductors from corrosion and other factors. Growth in the market of communication, smartphones, and tablets is boosting the growth of the semiconductor market growth. Moreover, growth in the electronics sector and surging demand semiconductors packaging from the electronics industry is further boosting the market growth. Continuous technological advancements in packaging material are increasing the demand for semiconductor packaging. Geographically, Asia Pacific region is expected to have a significant market share on account of the presence of key players of the electronics industry in the region. Moreover, the availability of low-cost labors in the region is attracting manufacturers towards the region. Also, demand for smartphones is rapidly increasing in the region which is contributing to the growth of semiconductors packaging material market in the region. The market of North America and Europe region is expected to witness rapid growth on account of increasing investment into the electronic industry by key players and increasing consumer electronic product penetration in the region.

An increasing cost of raw material and labor may hamper the growth of the market. However, technological advancements and product improvements by the manufacturers are expected to boost the market. Moreover, continuously increasing demand for smartphones will continue to increase the market size of semiconductors packaging material market in the coming years.

The Semiconductor packaging material market – Forecasts from 2019 to 2024 is an exhaustive study which aims to present the key market trends through various chapters

focusing on different aspects of the market. The study provides a detailed market overview through the market dynamics sections which detail key market, drivers, restraints, and opportunities in the current market. The report analyzes key opportunity regional markets, and the current technology penetration through lifecycle analysis. The report also analyzes the market through comprehensive market segmentation by type, technology, and geography.

The semiconductor packaging material market on segmented based on type, technology, and geography. Based on type the market has been segmented into organic substrates, bonding wires, lead frames, solder balls, wafer-level packaging dielectrics, and others. Based on technology the market has been segmented into grid array, small outline package, dual flat no-leads, quad flat package, dual in-line package, and others.

Regional analysis has been provided with detailed analysis and forecast for the period 2018 to 2024. The global market has been broken down into North America, South America, Europe, Middle East and Africa, and the Asia Pacific regions. The report also analyzes 13 countries across these regions with thorough analysis and forecast along with prevailing market trends and opportunities which each of these countries present for the manufacturers.

Major players in the semiconductor packaging material market have been covered along with their relative competitive position and strategies. The report also mentions recent deals and investments of different market players over the last year. The company profiles section details the business overview, financial performance for the past three years, key products and services being offered along with the recent developments of these important players in the semiconductor packaging material market.

Segmentation:

#### By Type

Organic Substrates

Bonding Wires

Lead frames

Solder Balls

Wafer-Level Packaging Dielectrics

Others

By Technology

Grid Array

Small Outline Package

Dual Flat No-Leads

Quad Flat Package

Dual In-Line Package

Others

By Geography

North America

USA

Canada

Mexico

South America

Brazil

Others

Europe

Germany

France

United Kingdom

Italy

Others

Middle East and Africa

Israel

Others

Asia Pacific

China

Japan

South Korea

India

Others

## Contents

### **1. INTRODUCTION**

- 1.1. Market Overview
- 1.2. Market Definition
- 1.3. Scope of the Study
- 1.4. Currency
- 1.5. Assumptions
- 1.6. Base, and Forecast Years Timeline

### **2. RESEARCH METHODOLOGY**

- 2.1. Research Design
- 2.2. Secondary Sources

### **3. EXECUTIVE SUMMARY**

### **4. MARKET DYNAMICS**

- 4.1. Market Segmentation
- 4.2. Market Drivers
- 4.3. Market Restraints
- 4.4. Market Opportunities
- 4.5. Porter's Five Forces Analysis
  - 4.5.1 Bargaining Power of Suppliers
  - 4.5.2 Bargaining Power of Buyers
  - 4.5.3 Threat of New Entrants
  - 4.5.4 Threat of Substitutes
  - 4.5.5 Competitive Rivalry in the Industry
- 4.6. Life Cycle Analysis - Regional Snapshot
- 4.7. Market Attractiveness

### **5. SEMICONDUCTOR PACKAGING MATERIAL MARKET BY TYPE**

- 5.1. Organic Substrates
- 5.2. Bonding Wires
- 5.3. Lead frames
- 5.4. Solder Balls

5.5. Wafer-Level Packaging Dielectrics

5.6. Others

## **6. SEMICONDUCTOR PACKAGING MATERIAL MARKET BY TECHNOLOGY**

6.1. Grid Array

6.2. Small Outline Package

6.3. Dual Flat No-Leads

6.4. Quad Flat Package

6.5. Dual In-Line Package

6.6. Others

## **7. SEMICONDUCTOR PACKAGING MATERIAL MARKET BY GEOGRAPHY**

7.1. North America

7.1.1. USA

7.1.2. Canada

7.1.3. Mexico

7.2. South America

7.2.1. Brazil

7.2.2. Others

7.3. Europe

7.3.1. United Kingdom

7.3.2. Germany

7.3.3. France

7.3.4. Italy

7.3.5. Others

7.4. Middle East and Africa

7.4.1. Israel

7.4.2. Others

7.5. Asia Pacific

7.5.1. China

7.5.2. Japan

7.5.3. South Korea

7.5.4. India

7.5.5. Others

## **8. COMPETITIVE INTELLIGENCE**

- 8.1. Market Positioning Matrix and Ranking
- 8.2. Recent Investments and Deals
- 8.3. Strategies of Key Players

## **9. COMPANY PROFILES**

- 9.1. Hitachi Chemical Co.
- 9.2. DuPont de Nemours, Inc.
- 9.3. Henkel Corporation
- 9.4. ASE Group
- 9.5. Sumitomo Chemical Co., Ltd.
- 9.6. KYOCERA Corporation
- 9.7. LG Chem.
- 9.8. Toray Industries, Inc.
- 9.9. SAMSUNG

## I would like to order

Product name: Semiconductor Packaging Materials Market - Forecasts from 2019 to 2024

Product link: <https://marketpublishers.com/r/SEE259008AF8EN.html>

Price: US\$ 3,950.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/SEE259008AF8EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:  
Last name:  
Email:  
Company:  
Address:  
City:  
Zip code:  
Country:  
Tel:  
Fax:  
Your message:

**\*\*All fields are required**

Customer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970